

## Type BMB-R Series

### Key Features

High Impedance at lower frequency

Prevents Signal ringing

Wide Frequency Characteristics

Suited to a variety of applications

Terminal finish matte Sn over Cu/Ni underplate



The BMB R Series has been designed for low speed applications and specifically for use in Digital Sound circuitry and similar to prevent ringing. These chip device have been designed to generate high impedances at low frequencies.

The R series is offered in three sizes 0603, 0805 and 1206

### Electrical Performance

Part Number	Impedance ( $\Omega$ ) at 100MHz	DC Resistance ( $\Omega$ ) maximum	Rated Current (mA) maximum
BMB-1J-0080R-S2	80 $\pm$ 25%	0.3	200
BMB-1J-0120R-S2	120 $\pm$ 25%	0.4	
BMB-1J-0240R-S2	240 $\pm$ 25%	0.5	
BMB-1J-0300R-S2	300 $\pm$ 25%	0.4	500
BMB-1J-0600R-S2	600 $\pm$ 25%	0.8	200
BMB-1J-1000R-S2	1000 $\pm$ 25%		
BMB-2A-0080R-S2	80 $\pm$ 25%	0.2	300
BMB-2A-0120R-S2	120 $\pm$ 25%	0.3	
BMB-2A-0240R-S2	240 $\pm$ 25%	0.4	
BMB-2A-0300R-S2	300 $\pm$ 25%	0.5	200
BMB-2A-0430R-S2	430 $\pm$ 25%		
BMB-2A-0600R-S2	600 $\pm$ 25%		
BMB-2A-1000R-S2	1000 $\pm$ 25%		

### Electrical Performance (continued)

Part Number	Impedance ( $\Omega$ ) at 100MHz * 50MHz * 30MHz	DC Resistance ( $\Omega$ ) maximum	Rated Current (mA) maximum
BMB-2B-0026R-S2	26 $\pm$ 25%	0.2	400
BMB-2B-0070R-S2	70 $\pm$ 25%	0.3	300
BMB-2B-0600R-S2	600 $\pm$ 25%	0.9	200

Operating temperature range - -55 ~ +125°C

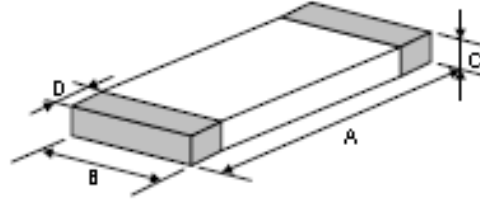
Temperature should be less than 25°C when rated current is applied.

Storage:

Temperature Range: -40 ~ +85°C

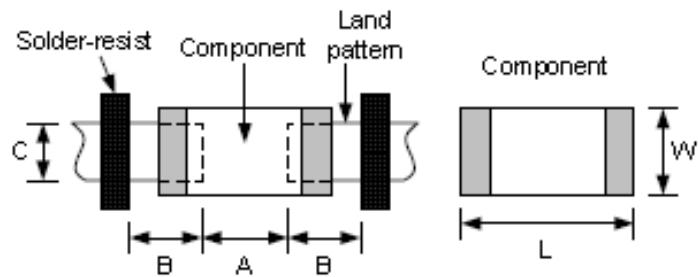
Humidity: Less than 75% RH

Product Dimensions



Size	A (mm)	B (mm)	C (mm)	D (mm)
0603	1.6 ±0.15	0.8 ±0.15	0.8 ±0.15	0.3 ±0.20
0805	2.0 ±0.20	1.2 ±0.20	0.9 ±0.20	0.5 ±0.30
1206	3.2 ±0.20	1.6 ±0.20	1.1 ±0.20	0.5 ±0.30

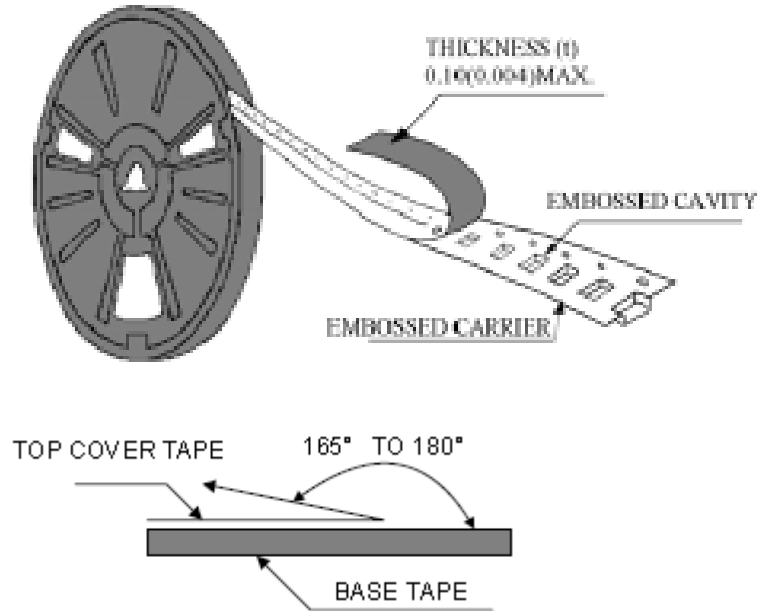
Recommended PCB Layout



Size	0603	0805	1206	
Component	L	1.6	2.0	3.2
	W	0.8	1.2	1.6
A	0.6 ~ 0.8	0.8 ~ 1.2	1.8 ~ 2.2	
B	0.6 ~ 0.8	0.8 ~ 1.2	1.1 ~ 2.2	
C	0.6 ~ 0.8	0.9 ~ 1.6	0.9 ~ 1.6	

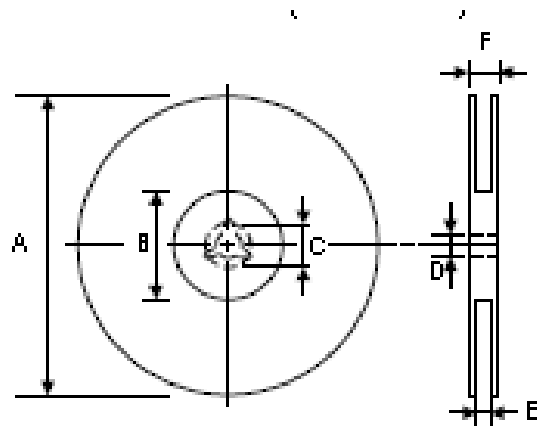
Packaging

Peel off force:

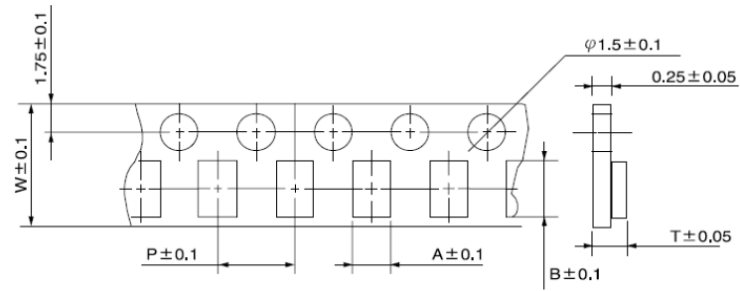


The force for peeling off cover tape is 10 grams in the direction shown

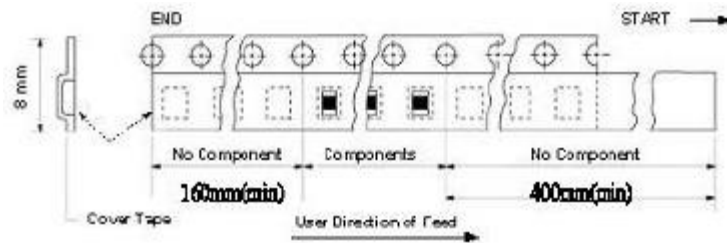
Dimensions (mm)



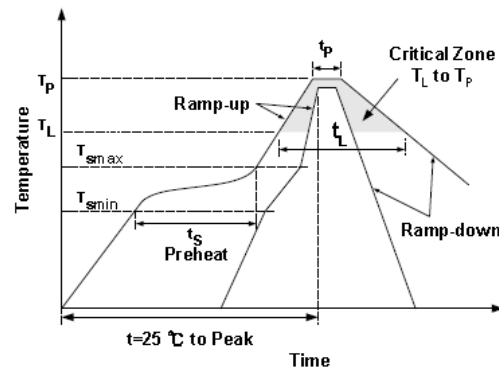
A	B	C	D	E	F
178 ±1	60 +0.5 -0.1	--	13 ±0.2	9 ±0.5	12 ±0.5



Size	A	B	W	P	T	Chips / Reel
0603	1.1	1.9	8	4	1.1	4000
0805	1.5	2.3	8	4	1.3	4000
1206	1.9	3.5	8	4	1.5	3000



## Recommended Reflow Solder Profile



Profile Feature		Pb Free
Preheat	ts	60 ~ 180 seconds
	Tsmin	150°C
	Tsmax	200°C
Average Ramp up rate (Tsmax to Tp)		3°C/second max.
Time main above	Temperature (TL)	217°C
	Time (tL)	60 ~ 150 seconds
Peak Temperature (Tp)		250 ~ 260°C
Time within 5°C of actual peak temperature ((tp)		10 seconds
Ramp down rate		6°C/second max.
Time 25°C to peak temperature		8 minutes max.

Typical Characteristic Curves (T=25°C)

